



**BOX AF**  
**R sp ns Under 37 C.F.R. 1.116**  
**Exp dited Proc dur Examining Group 2841**

PATENT  
Atty. Docket No. 0630-1210P

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

|             |                      |            |           |
|-------------|----------------------|------------|-----------|
| Applicant:  | Jae-Choon LEE et al. | Conf. No.: | 7426      |
| Appln. No.: | 09/764,208           | Group:     | 2841      |
| Filed:      | January 19, 2001     | Examiner:  | D.E. LEVI |
| For:        | ONE SYSTEM MODULE    |            |           |

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**AMENDMENT AFTER FINAL REJECTION**

Assistant Commissioner for Patents  
Washington, D.C. 20231

August 22, 2002

Sir:

In response to the Examiner's final Office Action dated May 22, 2002, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

***In The Claims***

Please amend claims 1, 3 and 5-6 as follows:

1. (Amended) A one system module in which a ceramic printed circuit board (PCB) and an epoxy PCB are disposed inside a module body, a power